

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
-	211	((wire or wiring) near5 (short or shorten or shortening or shorter)) and electrode.clm. and (wire or wiring).clm. and ((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:44
-	3	((wire or wiring) near5 (short or shorten or shortening or shorter)) and electrode.clm. and (wire or wiring).clm. and ((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and interposer.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:44
-	11	((wire or wiring) near5 (short or shorten or shortening or shorter)) and electrode.clm. and (wire or wiring).clm. and ((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:46
-	42	((wire or wiring) near5 (short or shorten or shortening or shorter)) and electrode.clm. and (wire or wiring).clm. and ((first or second or upper or lower or top or bottom) near3 (chip or ic) near5 (back or reverse or opposite)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:49
-	21	((wire or wiring) near5 (short or shorten or shortening or shorter)) and electrode.clm. and (wire or wiring).clm. and ((first or second or upper or lower or top or bottom) near3 (chip or ic) near5 (back or reverse or opposite)).clm. and (stack or stacking or stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:51
-	121	((hole or opening) same ((first or second or upper or lower or top or bottom) near3 (chip or ic)) same (wire or wiring) same electrode same (back or reverse or opposite))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:54
-	22	((hole or opening) same ((first or second or upper or lower or top or bottom) near3 (chip or ic)) same (wire or wiring) same electrode same (back or reverse or opposite)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 09:56
-	29	((hole or opening) same ((first or second or upper or lower or top or bottom) near3 (chip or ic)) same (wire or wiring) same electrode same (back or reverse or opposite)) and ((wire or wiring) near3 (short or shorten or shorter or shortening))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:19
-	41	interposer.clm. and electrode.clm. and (wire or wiring).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:20

-	6	interposer.clm. and electrode.clm. and (wire or wiring).clm. and (stack or stacking or stacked).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:20
-	14	interposer.clm. and electrode.clm. and (wire or wiring).clm. and (stack or stacking or stacked)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:26
-	4	((nonconducting or nonconductive or non-conducting or non-conductive) near interposer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:25
-	13582	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:27
-	273	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:27
-	122	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:28
-	4937	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:28
-	2	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:29
-	79	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and (interposer or glass)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:29
-	15	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and (interposer or glass).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:29

-	44	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and (interposer or glass or tape).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:30
-	0	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((nonconducting or non-conducting or nonconductive or non-conductive) near (interposer or glass or tape)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:30
-	0	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((nonconducting or non-conducting or nonconductive or non-conductive) near (interposer or glass or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:30
-	0	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and (stack or stacked or stacking) and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((nonconducting or non-conducting or nonconductive or non-conductive) near5 (interposer or glass or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:31
-	1	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((nonconducting or non-conducting or nonconductive or non-conductive) near5 (interposer or glass or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:31
-	80	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((interposer or glass or tape)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:31
-	29	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((interposer or glass or tape)).clm. and (electrode same (wire or wiring) same (chip or ic) same (hole or opening or through-hole) same (interposer or glass or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:32

-	21	((first or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and electrode.clm. and (wire or wiring).clm. and (hole or opening or through-hole).clm. and ((interposer or glass or tape)).clm. and (electrode same (wire or wiring) same (chip or ic) same (hole or opening or through-hole) same (interposer or glass or tape)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/21 10:37
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